Electronic Patent Application Fee Transmittal								
Application Number:	10534962							
Filing Date:	16-May-2005							
Title of Invention:	Circuit board, multi-layer wiring boards, method of producing circuit boards and method of producing multilayer wiring boards							
First Named Inventor/Applicant Name:	Masayoshi Kondo							
Filer:	Robert G. Weilacher/Susan Revell							
Attorney Docket Number:	033036.088							
Filed as Large Entity								
U.S. National Stage under 35 USC 371 Filing Fees								
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)			
Basic Filing:								
Pages:								
Claims:								
Miscellaneous-Filing:								
Petition:								
Patent-Appeals-and-Interference:								
Notice of appeal		1401	1	510	510			
Post-Allowance-and-Post-Issuance:								
Extension-of-Time:								

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension - 2 months with \$120 paid	1252	1	340	340
Miscellaneous:				
	Tot	850		